

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S29	0	10/695249	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 12:56
S30	12920	((opening trench hole via groove damascene recess) with substrate) with (diffusion diffus\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:45
S31	2815	S30 and ((opening trench hole via groove damascene recess) with substrate) with (barrier line lining seed)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:37
S32	1759	S31 and ((opening trench hole via groove damascene recess) with substrate) with (conduct\$3 metal\$5)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:44
S33	525	S32 and ((heat\$4 anneal\$4 thermal\$5) with (ion dopant activ\$4 dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 13:10
S34	83	S33 and (electroless plating electroplating)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 13:09
S35	596	S32 and ((heat\$4 anneal\$4 thermal\$5) with (impurity ion dopant activ\$4 dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 13:15
S36	407	S35 and (planar planized planarization polish\$3 'cmp' chemical adj mechanical)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:51
S37	192	S36 and ((opening trench hole via groove damascene recess) with (isulat\$4 dielectric))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 13:22
S38	52	S37 and boundary	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 16:10
S39	78	S37 and interface	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 13:24
S40	41	S37 and grain	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 13:23
S41	2241	S30 and ((opening trench hole via groove damascene recess) with substrate) with (metal)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:38
S42	139	S41 and ((opening trench hole via groove damascene recess) with substrate) with (refractory noble)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:40

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S43	4800	S30 and ((opening trench hole via groove damascene recess) with substrate) with (metal conduct\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:38
S44	139	S42 and ((opening trench hole via groove damascene recess) with substrate) with (refractory noble)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:43
S45	201	S41 and ((opening trench hole via groove damascene recess) with (refractory noble))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:40
S46	141	S43 and ((opening trench hole via groove damascene recess) with substrate) with (refractory noble)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:43
S47	12920	((opening trench hole via groove damascene recess) with substrate) with (diffusion diffus\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:45
S48	6640	S47 and ((opening trench hole via groove damascene recess) with (metal metall\$5 conduct\$3))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:47
S49	4169	S48 and ((opening trench hole via groove damascene recess) with (ion impurity dopant dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:49
S50	2011	S49 and ((heat\$3 anneal\$3 thermal) with (ion impurity dopant dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:48
S51	437	S50 and ((migrat\$3 interfac\$3 boundary) with (ion impurity dopant dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 16:00
S52	263	S51 and (planar planized planarization polish\$3 'cmp' chemical adj mechanical)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:52
S53	97	S52 and interconnect\$3	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 15:52
S54	382	S50 and ((interfac\$3 boundary) with (ion impurity dopant dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 16:00
S55	258	S50 and (interfac\$3 with (ion impurity dopant dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 16:01
S56	46	S55 and (boundary with (ion impurity dopant dop\$2))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/11 16:01
S57	0	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (diffs\$4 near3 process\$3)	USPAT	OR	OFF	2006/03/20 10:08

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S58	39	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (diffus\$4 near3 process\$3)	USPAT	OR	OFF	2006/03/20 10:12
S59	157	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (metal near3 diffus\$3)	USPAT	OR	OFF	2006/03/20 10:08
S60	145	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (alloy\$3 near3 process\$3)	USPAT	OR	OFF	2006/03/20 10:10
S61	300	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (alloy\$3 near3 process\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/20 10:14
S62	39	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (diffus\$4 near3 process\$3)	USPAT	OR	OFF	2006/03/20 10:12
S63	73	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (diffus\$4 near3 process\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/20 10:13
S64	99	(copper cu) with (ru rh au ag gold silver ruthenium rhodium os osmium ir iridium) with (diffus\$4 near3 process\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/03/20 10:12
S65	1	10/078243	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/20 12:25
S66	3	09/156903	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/20 13:19
S67	1	10/078243	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/20 13:20
S68	5	"6444567"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/29 09:37

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S69	52	("3826886" "3839727" "3839780" "3887994" "4319967" "4393096" "4565586" "4698233" "5071714" "5096508" "5258329" "5272015" "5296653" "5360995" "5378660" "5390141" "5455196" "5518936" "5547861" "5547881" "5565378" "5592024" "5656546" "5656860" "5788830" "5851922" "5885895" "5885896" "5898222" "5951922" "6030895" "6100195" "6107687" "6110819" "6110829" "6140236" "6146988" "6147000" "6171949" "6171960" "6174810" "6174812" "6214731" "6261939" "6261950" "6306750" "6323131" "6329722" "6358849" "6444567" "6468906" "6495200").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/29 09:43
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